



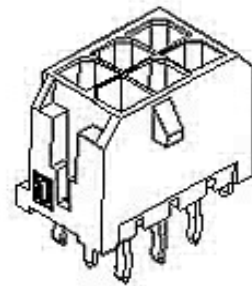
Part Number : [440670402](#)

Product Description : Micro-Fit 3.0 Wire-to-Board Header, Dual Row, Vertical for up to 3.56mm Thick PCB, 4 Circuits, 0.38µm Gold (Au) Selective Plating

Series Number : 44067

Status : Active

Product Category : PCB Headers and Receptacles



Documents & Resources

Drawings

[440670402_sd.pdf](#)

[PK-70873-0314-001.pdf](#)

3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

[Symbol and Footprint \(Multi-Format\)](#)

[SYM-44067-040X-001.zip](#)

Specifications

[430450001-PS-KO-000.pdf](#)

[430450001-PS-SP-000.pdf](#)

[PS-43045-001.pdf](#)

[430450005-TS-000.pdf](#)

[430450007-TS-000.pdf](#)

[TS-43045-001-001.pdf](#)

[TS-43045-002-001.pdf](#)

[TS-46235-001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
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China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	PCB Headers and Receptacles
Series	44067
Description	Micro-Fit 3.0 Wire-to-Board Header, Dual Row, Vertical for up to 3.56mm Thick PCB, 4 Circuits, 0.38µm Gold (Au) Selective Plating
Application	Power, Wire-to-Board
Comments	High Temperature, Polarization Key to PCB
Component Type	PCB Header
Product Name	Micro-Fit 3.0
UPC	800754773225

Agency

UL	E29179
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Electrical

Current - Maximum per Contact	8.5A
Voltage - Maximum	250V

Physical

Breakaway	No
Circuits (Loaded)	4
Circuits (maximum)	4
Color - Resin	Black
Durability (mating cycles max)	30
First Mate / Last Break	No
Flammability	94V-0
Glow-Wire Capable	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	0.741/g
Number of Rows	2
Orientation	Vertical
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	3.60mm
PC Tail Length	4.01mm
Pitch - Mating Interface	3.00mm
Pitch - Termination Interface	3.00mm
Plating min - Mating	0.381µm
Plating min - Termination	2.540µm
Polarized to PCB	Yes

Shrouded	Fully
Stackable	No
Temperature Range - Operating	-40° to +125°C
Termination Interface Style	Through Hole - Kinked Pin

Solder Process Data

Max-Duration	30
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	3
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Micro-Fit 3.0 Dual Row Receptacle Housings	<u>43025</u>

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